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PATENT
8026-1004

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Koki HIRASAWA et al.

Conf. 2347

Application No. 09/923,394

Group 2826

Filed August 8, 2001

Examiner F. Erdem

LEAD FRAME, SEMICONDUCTOR DEVICE
PRODUCED BY USING THE SAME AND METHOD
OF PRODUCING THE SEMICONDUCTOR DEVICE

SUPPLEMENAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the accompanying document, a copy of which is attached to this statement, is made of record on the enclosed Form PTO-1449.

A concise explanation of the relevance of this item is that this reference was cited by the Korean Patent Office in an Official Action. A copy of the Korean Official Action and Japanese translation in which it was cited is attached hereto. **An English translation is also attached hereto.**

Under the provisions of 37 CFR 1.97(e), the undersigned hereby certifies that each item of information contained in this Supplemental Information Disclosure Statement was first cited in any communication from a foreign Patent Of-

fice in a counterpart foreign application not more than three months prior to the filing of this Statement.

Respectfully submitted,

YOUNG & THOMPSON



Robert J. Patch, Reg. No. 17,355
745 South 23rd Street
Arlington, VA 22202
Telephone (703) 521-2297
Telefax (703) 685-0573
(703) 979-4709

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